NPN silicon planar epitaxial microwave power transistor

MX1011B400W

FEATURES

- Suitable for short and medium pulse applications up to 500 µs/10%
- Internal input and output prematching networks allow an easier design of circuits
- Diffused emitter ballasting resistors improve ruggedness
- Interdigitated emitter-base structure provides high emitter efficiency
- Gold metallization with barrier realizes very good stability of the characteristics and excellent lifetime
- Multicell geometry improves power sharing and reduces thermal resistance.

PINNING - FO-91B

PIN	DESCRIPTION				
1	collector				
2	emitter				
3	base connected to flange				

DESCRIPTION

NPN silicon planar epitaxial microwave power transistor intended for use in common base class C pulsed power amplifiers. The transistor has a FO-91B metal ceramic flange package with base connected to flange.

APPLICATIONS

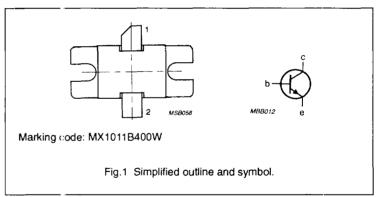
Intended for use in common base class C broadband pulsed power amplifiers for TCAS applications in the 1030 to 1090 MHz band. Also suitable for medium pulse, heavy duty operation within this band.

QUICK REFERENCE DATA

Microwave performance up to $T_{mb} = 25$ °C in a common base class C narrow band amplifier.

MODE OF OPERATION	CONDITIONS	f (GHz)	V _{cc} (V)	P _L (W)	G _p (dB)	η c (%)
class C	$t_p = 30 \mu s;$ $\delta = 1\%$	1.03	45	≥ 450	≥ 6.5	≥ 42

PIN CONFIGURATION



WARNING

Product and environmental safety - toxic materials

This product contains beryllium oxide. The product is entirely safe provided that the BeO slab is not damaged. All persons who handle, use or dispose of this product should be aware of its nature and of the necessary safety precautions. After use, dispose of as chemical or special waste according to the regulations applying at the location of the user. It must never be thrown out with the general or domestic waste.

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LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	65	V
V _{CEO}	collector-emitter voltage	open base	-	20	V
V _{CES}	collector-emitter voltage	$R_{BE} = 0 \Omega$	-	65	٧
V _{EBO}	emitter-base voltage	open collector	-	3	V
Ic	average collector current	$t_p \le 30 \ \mu s;$ $\delta \le 1\%$		35	A
P _{tot}	total power dissipation	$T_{mb} < 75 ^{\circ}\text{C};$ $t_{p} \le 30 \mu\text{s};$ $\delta \le 1\%$	-	1200	W
T _{stg}	storage temperature range		-65	200	° C
T,	operating junction temperature			200	° C
T _{sid}	soldering temperature	t ≤ 10 s note 1	_	235	° C

Note

1. Up to 0.2 mm from ceramic.

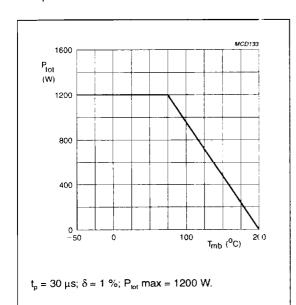


Fig.2 Maximum power dissipation derating as a function of mounting base temperature.